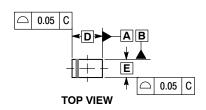
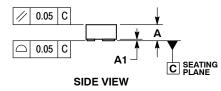


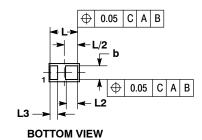


DSN2, 1.0x0.6, 0.575P, (0402) CASE 152AC ISSUE D

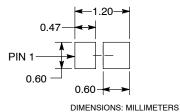
DATE 27 APR 2017







RECOMMENDED **SOLDER FOOTPRINT***



See Application Note AND8464/D for more mounting details

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.25	0.31	
A1		0.05	
b	0.45	0.55	
D	1.00 BSC		
E	0.60 BSC		
L	0.85	0.95	
L2	0.35	0.45	
L3	0.20	0.30	

GENERIC MARKING DIAGRAM1*

GENERIC MARKING DIAGRAM2*



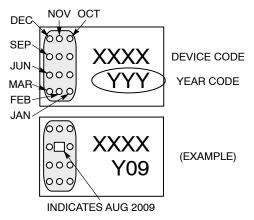


XXXX = Specific Device Code YYY = Year Code

XX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

CATHODE BAND MONTH CODING



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DESCRIPTION:	DSN2, 1.0X0.6, 0.575P, (0402)		PAGE 1 OF 1

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.